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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Shih-Wei Chou, et al.

Serial No.: 10/763,306

Filed:

January 23, 2004

For:

Method to Improve Planarity of

Electroplated Copper

Docket No.:

2001-1503/24061.433

Customer No.

42717

Group Art Unit:

2813

Examiner:

Rodgers, Colleen E.

Conf. No.

6528

TRANSMITTAL

Mail Stop: Amendments Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

- 1. Amendment to the Non-Final Office Action dated November 1, 2005;
- 2. This transmittal (in duplicate); and
- 3. Return postcard.

Applicant believes no fee is due. However, the Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell

Reg. No. 42,044

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HAYNES AND BOONE, LLP

Customer Number: 42717

Date: January 6, 2006

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with

the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450,

Alexandria, VA 22313-1450 on the date indicated below:

Bonnie Boyle

January 6, 2006

Date

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Commissioner for Patents Mail Stop Amendment P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office action of November 1, 2005, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 11 of this paper.